

PCN Number: PCN-01237		PCN Date: April 22, 2019	
Title: Change to MAAP-011233 Lid Attach Epoxy			
Date of change: May 2019 Proposed last Ship Date:		Estimated Sample Availability/Qualification Completion: On request See QTR-0467	
Change Classification:		Minor <input checked="" type="checkbox"/>	
Change Type:			
Assembly Site <input type="checkbox"/>	Design <input type="checkbox"/>	Electrical Specification <input type="checkbox"/>	
Test Site <input type="checkbox"/>	Assembly Process <input type="checkbox"/>	Mechanical Specification <input type="checkbox"/>	
Wafer Process <input type="checkbox"/>	Assembly Materials <input checked="" type="checkbox"/>	Packing/Shipping/Labeling <input type="checkbox"/>	
PCN Details			
Description of Change:			
A minor change is being made to the lid attach epoxy. The epoxy is being changed from Epo-Tek B9021-15 to Epo-Tek 131-8-1.			
Reason for Change:			
The lid attach epoxy is being changed to increase the lid shear strength of the device.			
Products Affected:			
MAAP-011233 MAAP-011233-TR0500 MAAP-011233-TR1000			
Anticipated impact on Fit, Form, Function:			
No changes to fit, form, or function. Enhanced product reliability is expected.			
Changes to product identification resulting from this PCN:			
None			
Material Declaration updated due to this change:		Yes <input checked="" type="checkbox"/> No <input type="checkbox"/>	